


L8  L7

214  216

L4

ON 14 NOV 2002

~~$\begin{array}{c} \text{H}_2 \quad \text{H} \\ \text{C} = \text{C} \\ | \\ \text{C} = \text{O} \\ | \\ \text{O} \\ | \\ \text{Y} \\ | \\ \text{O} \\ | \\ \text{R} \end{array}$~~

L18

9-24-02

comps.)

Do Not Remove

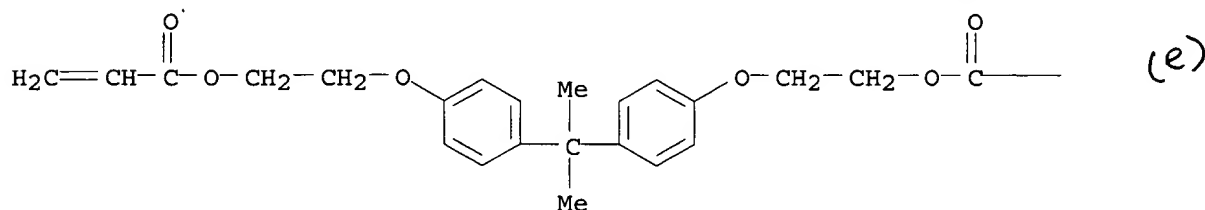
RN 374106-03-3 USPATFULL
CN 2-Propenoic acid, (1-methylethylidene)bis(4,1-phenyleneoxy-2,1-ethanediyl)
ester, polymer with phenylmethyl 2-propenoate and (tetrahydro-2-
furanyl)methyl 2-propenoate (9CI) (CA INDEX NAME)

CM 1

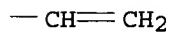
CRN 24447-78-7

CMF C25 H28 O6

PAGE 1-A



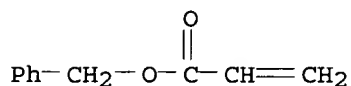
PAGE 1-B



CM 2

CRN 2495-35-4

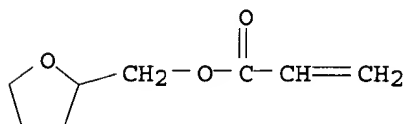
CMF C10 H10 O2



CM 3

CRN 2399-48-6

CMF C8 H12 O3



AB The invention provides compositions for producing lenses by casting. The compositions are useful in producing ophthalmic lens by casting of a surface or layer onto a preform.

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L22 ANSWER 2 OF 8 USPATFULL

ACCESSION NUMBER: 2001:126043 USPATFULL

TITLE: Homopolymers containing stable elasticity inducing crosslinkers and ocular implants made therefrom
 INVENTOR(S): Liao, Xiugao, Irvine, CA, United States
 Gulati, Vijay, Lake Forest, CA, United States
 PATENT ASSIGNEE(S): Medennium, Inc., Irvine, CA, United States (U.S. corporation)

	NUMBER	KIND	DATE
PATENT INFORMATION:	US 6271281	B1	20010807
APPLICATION INFO.:	US 1999-383837		19990826 (9)
DOCUMENT TYPE:	Utility		
FILE SEGMENT:	GRANTED		
PRIMARY EXAMINER:	Yoon, Tae H.		
LEGAL REPRESENTATIVE:	Oppenheimer Wolff & Donnelly, LLP		
NUMBER OF CLAIMS:	1		
EXEMPLARY CLAIM:	1		
LINE COUNT:	1013		

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

IT 328238-44-4P

(homopolymers contg. crosslinkers and ocular implants made therefrom)

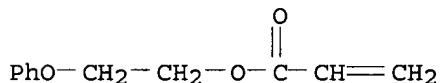
RN 328238-44-4 USPATFULL

CN 2-Propenoic acid, 2-(4-benzoyl-3-hydroxyphenoxy)ethyl ester, polymer with .alpha.,.alpha.'-[(1-methylethylidene)di-4,1-phenylene]bis[.omega.-[(2-methyl-1-oxo-2-propenyl)oxy]poly[oxy(methyl-1,2-ethanediyl)]] and 2-phenoxyethyl 2-propenoate (9CI) (CA INDEX NAME)

CM 1

CRN 48145-04-6

CMF C11 H12 O3



CM 2

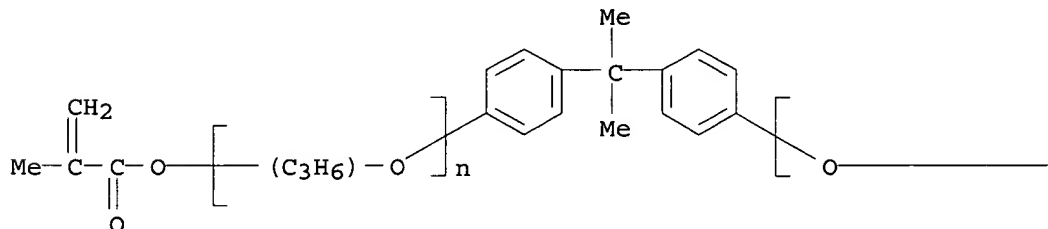
CRN 42610-22-0

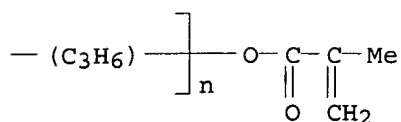
CMF (C3 H6 O)_n (C3 H6 O)_n C23 H24 O4

CCI IDS, PMS

CDES 8:ID

PAGE 1-A

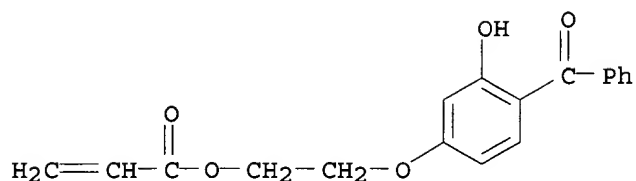




CM 3

CRN 16432-81-8

CMF C18 H16 O5



AB Ocular implants composed of homopolymers containing stable elasticity inducing crosslinkers which contain rigid chemical groups disposed between at least two polymerizable ethyleneically unsaturated chemical groups are disclosed. These ocular implants are stable, elastic, soft, optically clear, have high refractive index and low-tack surfaces.

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L22 ANSWER 3 OF 8 USPATFULL

ACCESSION NUMBER: 2001:48132 USPATFULL
 TITLE: Photocurable paint composition for road markings
 INVENTOR(S): Nakamura, Kenichi, Ohmiya, Japan
 Kamata, Hirotooshi, Chiba, Japan
 Koshikawa, Toshio, Chiba, Japan
 Sugita, Shuichi, Tokyo, Japan
 PATENT ASSIGNEE(S): Showa Denko K.K., Tokyo, Japan (non-U.S. corporation)

	NUMBER	KIND	DATE
PATENT INFORMATION:	US 6211260	B1	20010403
APPLICATION INFO.:	US 1998-185583		19981104 (9)

4/3/01

	NUMBER	DATE
PRIORITY INFORMATION:	JP 1997-303081	19971105
	US 1998-86141P	19980520 (60)

DOCUMENT TYPE: Utility
 FILE SEGMENT: Granted
 PRIMARY EXAMINER: Berman, Susan W.
 LEGAL REPRESENTATIVE: Sughrue, Mion, Zinn, Macpeak & Seas, PLLC
 NUMBER OF CLAIMS: 7
 EXEMPLARY CLAIM: 1
 LINE COUNT: 1121

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

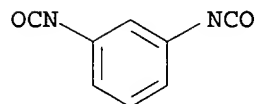
IT 224628-00-6P

(cured paint; photocurable paint compn. for road markings)

RN 224628-00-6 USPATFULL
 CN 2-Propenoic acid, 1,6-hexanediyl ester, polymer with 1,3-diisocyanatomethylbenzene, 2-hydroxy-3-phenoxypropyl 2-propenoate and rel-(1R,2R,4R)-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl 2-propenoate (9CI)
 (CA INDEX NAME)

CM 1

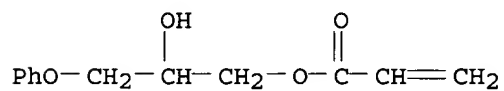
CRN 26471-62-5
 CMF C9 H6 N2 O2
 CCI IDS
 CDES 8:ID



D1-Me

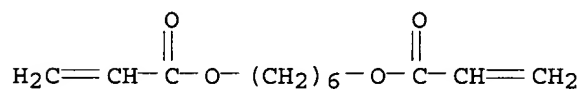
CM 2

CRN 16969-10-1
 CMF C12 H14 O4



CM 3

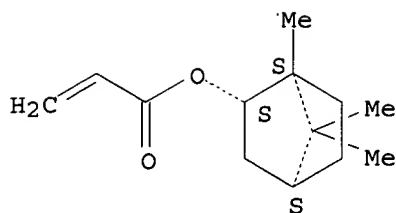
CRN 13048-33-4
 CMF C12 H18 O4



CM 4

CRN 5888-33-5
 CMF C13 H20 O2
 CDES 2:EXO

Relative stereochemistry.



AB A photocurable paint composition for road markings is disclosed, comprising (A) a compound having an ethylenically unsaturated group, (B) a filler, (C) a cationic dye represented by formula (1):

D.sup.+ .circle-solid. A.sub.1.sup.- (1)

(wherein D.sup.+ represents a cation having an absorption maximum wavelength in the wavelength region of from 400 to 1,200 nm, and A.sub.1.sup.- represents an optional anion), (D) a quaternary organic borate-type sensitizer represented by formula (2): ##STR1##

(wherein R.sub.1, R.sub.2, R.sub.3 and R.sub.4 each independently represents an alkyl group, an aryl group, an aralkyl group, an alkenyl group, an alkynyl group, a silyl group, a heterocyclic group or a halogen atom, and Z.sup.+ represents an optional cation) and (E) an ultraviolet radical polymerization initiator capable of generating a radical upon absorption of light at a wavelength of 400 nm or less, or additionally comprising (F) glass beads.

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L22 ANSWER 4 OF 8 USPATFULL

ACCESSION NUMBER: 2000:98478 USPATFULL
 TITLE: Quinolinium dyes and borates in photopolymerizable compositions
 INVENTOR(S): Cunningham, Allan Francis, Mount Kisco, NY, United States
 Kunz, Martin, Efringen-Kirchen, Germany, Federal Republic of
 PATENT ASSIGNEE(S): Ciba Specialty Chemicals Corporation, Tarrytown, NY, United States (U.S. corporation)

	NUMBER	KIND	DATE
PATENT INFORMATION:	US 6096794		20000801
APPLICATION INFO.:	US 1998-179170		19981026 (9)

8/1/00

	NUMBER	DATE
PRIORITY INFORMATION:	EP 1997-810820	19971103
DOCUMENT TYPE:	Utility	
FILE SEGMENT:	Granted	
PRIMARY EXAMINER:	Berman, Susan W.	
LEGAL REPRESENTATIVE:	Hall, Luther A. R., Stevenson, Tyler A.	
NUMBER OF CLAIMS:	21	
EXEMPLARY CLAIM:	1	
LINE COUNT:	2738	

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

IT 225225-94-5P

(quinolinium dyes and borates in photopolymerizable compds.)

RN 225225-94-5 USPATFULL

CN 2-Propenoic acid, 2-ethyl-2-[[[(1-oxo-2-propenyl)oxy]methyl]-1,3-propanediyl ester, polymer with Actilane 200, ethenylbenzene, 2,5-furandione and .alpha.-(1-oxo-2-propenyl)-.omega.-[(1-oxo-2-

propenyl) oxy]poly(oxy-1,2-ethanediyl) (9CI) (CA INDEX NAME)

CM 1

CRN 225225-82-1

CMF Unspecified

CCI PMS, MAN

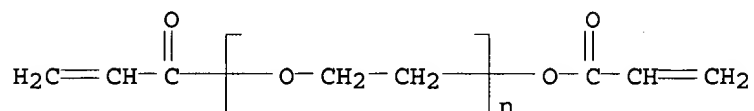
STRUCTURE DIAGRAM IS NOT AVAILABLE

CM 2

CRN 26570-48-9

$$\text{CMF} \quad (\text{C}_2 \text{ H}_4 \text{ O})_n \text{ C}_6 \text{ H}_6 \text{ O}_3$$

CCI PMS

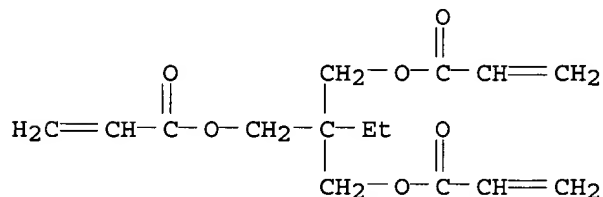


CM 3

CRN 15625-89-5

CMF C15 H20 O6

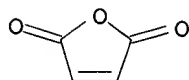
no norbornene



CM 4

CRN 108-31-6

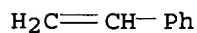
CMF C4 H2 O3



CM 5

CRN 100-42-5

CMF C8 H8



AB Dye compounds of the formula ##STR1## wherein X is for example CH,
C--CH.sub.3 or .sup.+ NOR L.sup.- ; R is inter alia C.sub.1 -C.sub.6
alkyl; R.sub.1 is for example C.sub.1 -C.sub.8 alkoxy or C.sub.1

-C.sub.12 alkyl; s is 0 to 4; R.sub.2 is for example hydrogen; Ar is for example a group ##STR2## Y inter alia is C.sub.1 -C.sub.6 alkyl or C.sub.1 -C.sub.6 alkoxy; r in the formula (A) is 0 to 5, in the formulae (B) and (E) is 0 to 9 and in the formula (D) is 0 to 7; and L is an anion;

in combination with an electron donor compound, especially a borate compound, are suitable as photoinitiators for the photopolymerization of radically polymerizable compositions.

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L22 ANSWER 5 OF 8 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER: 1999:665470 CAPLUS

DOCUMENT NUMBER: 131:294248

TITLE: Manufacture of semiconductor device and pressure-sensitive adhesive sheet for surface protecting in the manufacture

INVENTOR(S): Namikawa, Akira; Okawa, Takeshi; Nukaga, Jiro; Akata, Yuza

PATENT ASSIGNEE(S): Nitto Denko Corp., Japan

SOURCE: Jpn. Kokai Tokkyo Koho, 5 pp.

CODEN: JKXXAF

DOCUMENT TYPE: Patent

LANGUAGE: Japanese

FAMILY ACC. NUM. COUNT: 1

PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 11288907	A2	19991019	JP 1998-348108	19981208
EP 926732	A2	19990630	EP 1998-123429	19981209
EP 926732	A3	20010103		

R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO

PRIORITY APPLN. INFO.: JP 1997-340018 A 19971210

IT 246849-35-4P, Acrylic acid-butyl acrylate-dipentaerythritol hexaacrylate-diphenylmethane diisocyanate-ethyl acrylate-polyethylene glycol diacrylate-trimethylolpropane triacrylate copolymer
RL: IMF (Industrial manufacture); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(manuf. of semiconductor device involving polishing in protecting circuit surface using pressure-sensitive adhesive sheet)

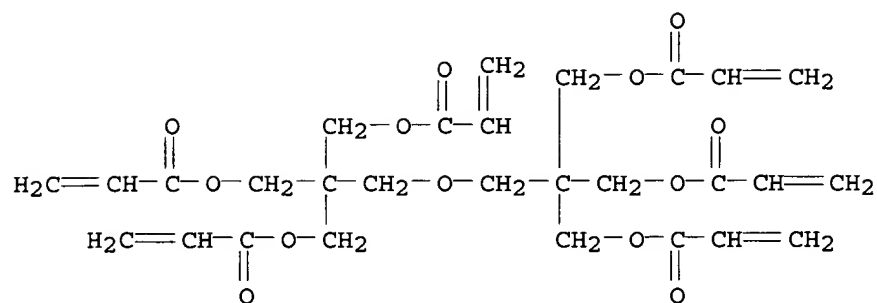
RN 246849-35-4 CAPLUS

CN 2-Propenoic acid, polymer with butyl 2-propenoate, 2-ethyl-2-[(1-oxo-2-propenyl)oxy]methyl]-1,3-propanediyl di-2-propenoate, ethyl 2-propenoate, 1,1'-methylenebis[4-isocyanatobenzene], .alpha.-(1-oxo-2-propenyl)-.omega.-[(1-oxo-2-propenyl)oxy]poly(oxy-1,2-ethanediyl) and 2-[[3-[(1-oxo-2-propenyl)oxy]-2,2-bis[[[(1-oxo-2-propenyl)oxy]methyl]propoxy]methyl]-2-[(1-oxo-2-propenyl)oxy]methyl]-1,3-propanediyl di-2-propenoate, graft (9CI)
(CA INDEX NAME)

CM 1

CRN 29570-58-9

CMF C28 H34 O13

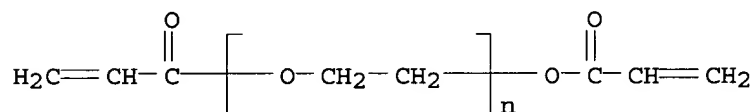


CM 2

CRN 26570-48-9

CMF (C2 H4 O)_n C6 H6 O3

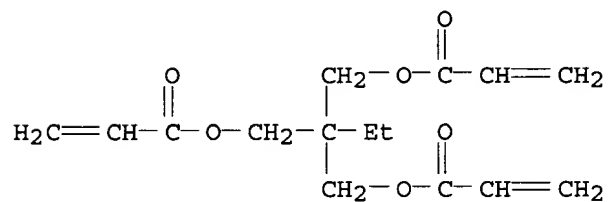
CCI PMS



CM 3

CRN 15625-89-5

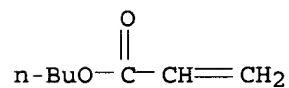
CMF C15 H20 O6



CM 4

CRN 141-32-2

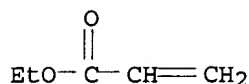
CMF C7 H12 O2



CM 5

CRN 140-88-5

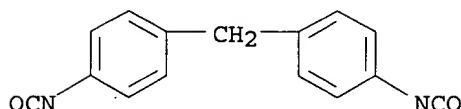
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CM 6

CRN 101-68-8

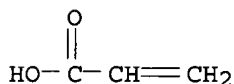
CMF C15 H10 N2 O2



CM 7

CRN 79-10-7

CMF C3 H4 O2



AB The semiconductor device is manufd. by a process including (a) attaching a pressure-sensitive adhesive surface-protecting sheet on the surface of 1 side of a semiconductor wafer having a circuit and a **resist** film on the surface, (b) polishing the opposite side of the wafer, and (c) releasing the sheet assocd. with the **resist** film which is transfered on the releasing sheet. The process saves some steps involved in conventional method and prevents the wafer surface from being affected by water in polishing.

L22 ANSWER 6 OF 8 CAPLUS COPYRIGHT 2002 ACS

ACCESSION NUMBER: 1999:140950 CAPLUS

DOCUMENT NUMBER: 130:230053

TITLE: Method for formation of ceramic partition wall for display panel involving **resist** removal by acid solution

INVENTOR(S): Sato, Hiroaki

PATENT ASSIGNEE(S): Nippon Synthetic Chemical Industry Co., Ltd., Japan

SOURCE: Jpn. Kokai Tokkyo Koho, 7 pp.

CODEN: JKXXAF

DOCUMENT TYPE: Patent

LANGUAGE: Japanese

FAMILY ACC. NUM. COUNT: 1

PATENT INFORMATION:

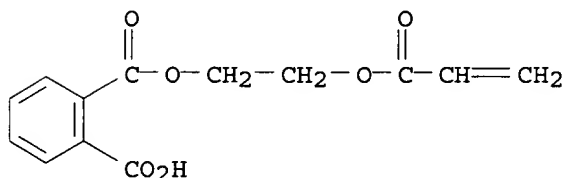
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	JP 11052588	A2	19990226	JP 1997-227519	19970808
IT	220929-70-4, 2-Acryloyloxyethyl phthalate-n-butyl methacrylate-ethoxylated trimethylolpropane triacrylate-2-ethylhexyl acrylate-methacrylic acid-methyl methacrylate-propylene glycol diacrylate copolymer				
	RL: DEV (Device component use); USES (Uses) (light-sensitive resin layer for glass or ceramic partition wall)				
RN	220929-70-4 CAPLUS				

CN 1,2-Benzenedicarboxylic acid, mono[2-[(1-oxo-2-propenyl)oxy]ethyl] ester, polymer with butyl 2-methyl-2-propenoate, 2-ethylhexyl 2-propenoate, .alpha.-hydro-.omega.-[(1-oxo-2-propenyl)oxy]poly(oxy-1,2-ethanediyl) ether with 2-ethyl-2-(hydroxymethyl)-1,3-propanediol (3:1), 1-methyl-1,2-ethanediyl di-2-propenoate, methyl 2-methyl-2-propenoate and 2-methyl-2-propenoic acid (9CI) (CA INDEX NAME)

CM 1

CRN 30697-40-6

CMF C13 H12 O6



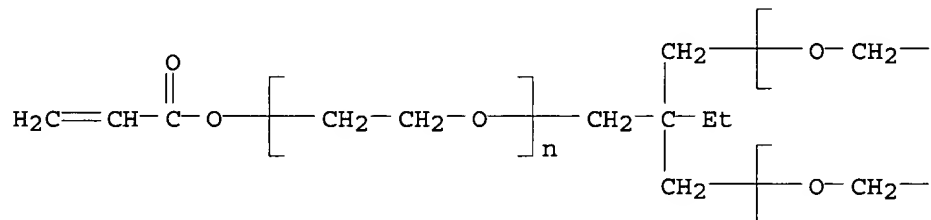
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CRN 28961-43-5

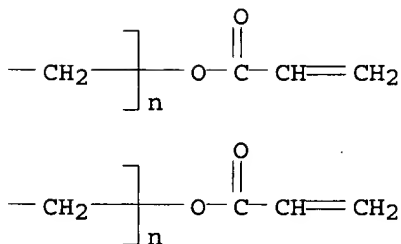
CMF (C2 H4 O)_n (C2 H4 O)_n (C2 H4 O)_n C15 H20 O6

CCI PMS

PAGE 1-A



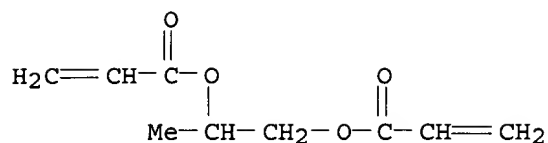
PAGE 1-B



CM 3

CRN 25151-33-1

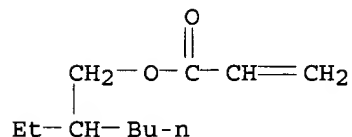
CMF C9 H12 O4



CM 4

CRN 103-11-7

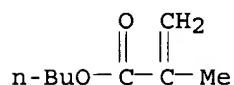
CMF C11 H20 O2



CM 5

CRN 97-88-1

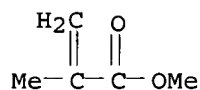
CMF C8 H14 O2



CM 6

CRN 80-62-6

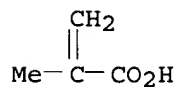
CMF C5 H8 O2



CM 7

CRN 79-41-4

CMF C4 H6 O2



AB The process comprises the steps of: (1) forming a light-sensitive resin layer; (2) exposing and developing the resin layer to form an intaglio pattern; (3) filling a ceramic material into the intaglio part; (4) drying and hardening the ceramic material; (4) removing the light-sensitive material using .ltoreq. pH 5 acidic soln.; and (5) baking the ceramic to form a lib-type partition wall. The method provides a precise pattern.

ACCESSION NUMBER: 1999:665470 HCAPLUS

DOCUMENT NUMBER: 131:294248

TITLE: Manufacture of semiconductor device and pressure-sensitive adhesive sheet for surface protecting in the manufacture

INVENTOR(S): Namikawa, Akira; Okawa, Takeshi; Nukaga, Jiro; Akata, Yuzo

PATENT ASSIGNEE(S): Nitto Denko Corp., Japan

SOURCE: Jpn. Kokai Tokkyo Koho, 5 pp.

CODEN: JKXXAF

DOCUMENT TYPE: Patent

LANGUAGE: Japanese

FAMILY ACC. NUM. COUNT: 1

PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 11288907	A2	19991019	JP 1998-348108	19981208
EP 926732	A2	19990630	EP 1998-123429	19981209
EP 926732	A3	20010103		

R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO

PRIORITY APPLN. INFO.: JP 1997-340018 A 19971210

IT 246849-35-4P, Acrylic acid-butyl acrylate-dipentaerythritol hexaacrylate-diphenylmethane diisocyanate-ethyl acrylate-polyethylene glycol diacrylate-trimethylolpropane triacrylate copolymer
 RL: IMF (Industrial manufacture); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)

(manuf. of semiconductor device involving polishing in protecting circuit surface using pressure-sensitive adhesive sheet)

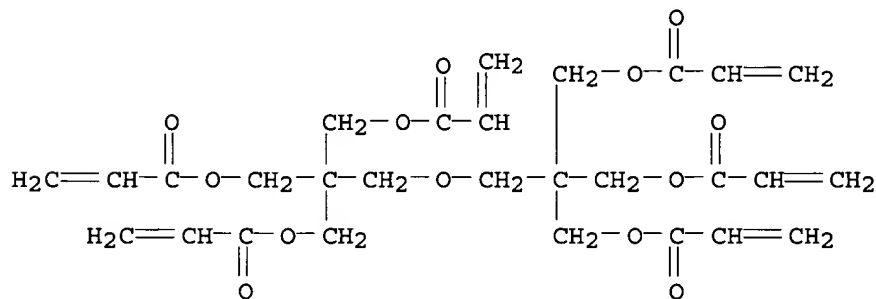
RN 246849-35-4 HCAPLUS

CN 2-Propenoic acid, polymer with butyl 2-propenoate, 2-ethyl-2-[(1-oxo-2-propenyl)oxy]methyl]-1,3-propanediyl di-2-propenoate, ethyl 2-propenoate, 1,1'-methylenebis[4-isocyanatobenzene], .alpha.-(1-oxo-2-propenyl)-.omega.-[(1-oxo-2-propenyl)oxy]poly(oxy-1,2-ethanediyl) and 2-[[3-[(1-oxo-2-propenyl)oxy]-2,2-bis[[[(1-oxo-2-propenyl)oxy]methyl]propoxy]methyl]-2-[[[(1-oxo-2-propenyl)oxy]methyl]-1,3-propanediyl di-2-propenoate, graft (9CI)
 (CA INDEX NAME)

CM 1

CRN 29570-58-9

CMF C28 H34 O13

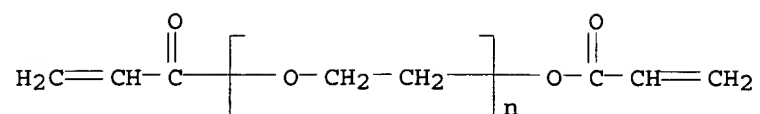


CM 2

CRN 26570-48-9

CMF (C2 H4 O)_n C6 H6 O3

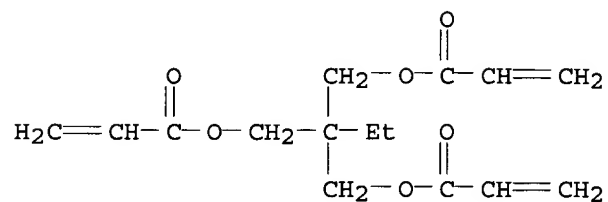
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CRN 15625-89-5

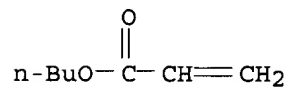
CMF C15 H20 O6



CM 4

CRN 141-32-2

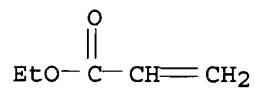
CMF C7 H12 O2



CM 5

CRN 140-88-5

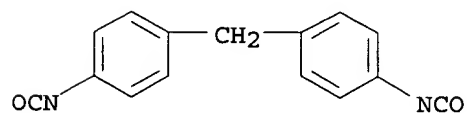
CMF C5 H8 O2



CM 6

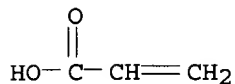
CRN 101-68-8

CMF C15 H10 N2 O2



CM 7

CRN 79-10-7
CMF C3 H4 O2



AB The semiconductor device is manufd. by a process including (a) attaching a pressure-sensitive adhesive surface-protecting sheet on the surface of 1 side of a semiconductor wafer having a circuit and a **resist** film on the surface, (b) polishing the opposite side of the wafer, and (c) releasing the sheet assocd. with the **resist** film which is transfered on the releasing sheet. The process saves some steps involved in conventional method and prevents the wafer surface from being affected by water in polishing.

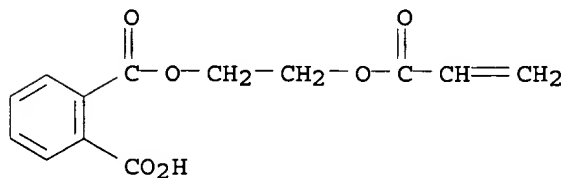
L22 ANSWER 8 OF 8 HCAPLUS COPYRIGHT 2002 ACS

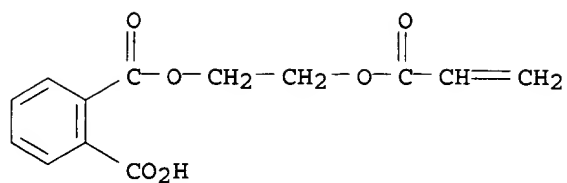
ACCESSION NUMBER: 1999:140950 HCAPLUS
DOCUMENT NUMBER: 130:230053
TITLE: Method for formation of ceramic partition wall for display panel involving **resist** removal by acid solution
INVENTOR(S): Sato, Hiroaki
PATENT ASSIGNEE(S): Nippon Synthetic Chemical Industry Co., Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 7 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
	-----		-----	-----	-----
	JP 11052588	A2	19990226	JP 1997-227519	19970808
IT	220929-70-4, 2-Acryloyloxyethyl phthalate-n-butyl methacrylate-ethoxylated trimethylolpropane triacrylate-2-ethylhexyl acrylate-methacrylic acid-methyl methacrylate-propylene glycol diacrylate copolymer				
	RL: DEV (Device component use); USES (Uses) (light-sensitive resin layer for glass or ceramic partition wall)				
RN	220929-70-4 HCAPLUS				
CN	1,2-Benzenedicarboxylic acid, mono[2-[(1-oxo-2-propenyl)oxy]ethyl] ester, polymer with butyl 2-methyl-2-propenoate, 2-ethylhexyl 2-propenoate, .alpha.-hydro-.omega.-[(1-oxo-2-propenyl)oxy]poly(oxy-1,2-ethanediyl) ether with 2-ethyl-2-(hydroxymethyl)-1,3-propanediol (3:1), 1-methyl-1,2-ethanediyl di-2-propenoate, methyl 2-methyl-2-propenoate and 2-methyl-2-propenoic acid (9CI) (CA INDEX NAME)				

CM 1

CRN 30697-40-6
CMF C13 H12 O6





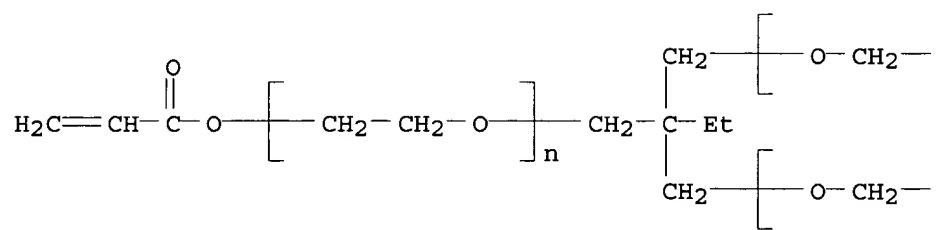
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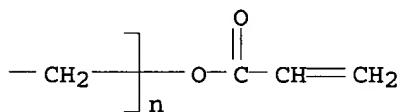
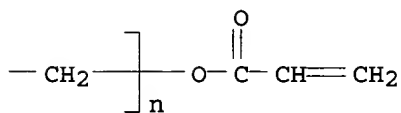
CMF (C2 H4 O)_n (C2 H4 O)_n (C2 H4 O)_n C15 H20 O6

CCI PMS

PAGE 1-A



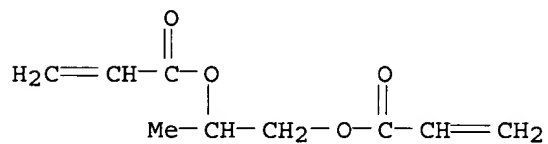
PAGE 1-B



CM 3

CRN 25151-33-1

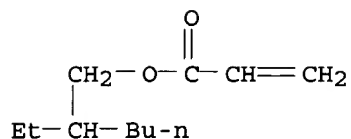
CMF C9 H12 O4



CM 4

CRN 103-11-7

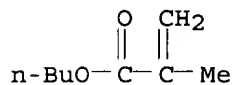
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CM 5

CRN 97-88-1

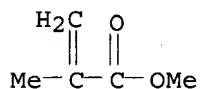
CMF C8 H14 O2



CM 6

CRN 80-62-6

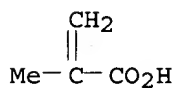
CMF C5 H8 O2



CM 7

CRN 79-41-4

CMF C4 H6 O2



AB The process comprises the steps of: (1) forming a light-sensitive resin layer; (2) exposing and developing the resin layer to form an intaglio pattern; (3) filling a ceramic material into the intaglio part; (4) drying and hardening the ceramic material; (4) removing the light-sensitive material using .ltoreq. pH 5 acidic soln.; and (5) baking the ceramic to form a lib-type partition wall. The method provides a precise pattern.